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Dolan et al.

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(54) **PROCESS AND STRUCTURE TO UNCURL EMBOSSED THIN FLEX CIRCUITS**

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See application file for complete search history.

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(57) **ABSTRACT**

A method and structure for flattening or straightening a curled flexible printed circuit, such as a flexible printed circuit that has been curled during a contact embossing process. The structure can include a cylindrical opening and a support shaft suspended within the cylindrical opening that prevents buckling of the flexible printed circuit during straightening. To flatten the curled flexible printed circuit, the curled end of the flexible printed circuit can be inserted into the cylindrical opening until the curled end is wrapped partially or completely around the support shaft.

(58) **Field of Classification Search**
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6 Claims, 3 Drawing Sheets

